

566.41199X00

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): FUJINAWA, et al.

5/A

Serial No.: 10/069,053

Filed: February 21, 2002

entered - 6-27-03 - RG

For: WIRING-CONNECTED MATERIAL AND WIRING-
CONNECTED BOARD PRODUCTION PROCESS USING
THE SAMEPRELIMINARY AMENDMENTAssistant Commissioner for Patents
Washington, D.C. 20231

May 21, 2002

Sir:

Please amend the above-identified application, prior to examination
thereof, as follows:IN THE CLAIMS

Please amend the claims presently in the application as follows:

A¹

6. (Amended) The wiring-connecting material according to any one
of claims 1 to 3, wherein said curing agent has a weight retention at 25°C for 24
hours, of not less than 20% by weight.

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